

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-20 (Canceled)

21. (New) A method of fabricating an electronic package, the method comprising:
 securing a die to an interposer; and
 securing a laminated conductor to the interposer to supply current to the die and
mechanically support the interposer, wherein securing a laminated conductor to the interposer
includes securing a positive portion of the laminated conductor to a positive section of the
interposer and securing a negative portion of the laminated conductor to a negative section of the
interposer
22. (New) The method recited in claim 21, wherein securing the laminated conductor to the
interposer includes securing the laminated conductor to the interposer on a side of the interposer
that includes the die.
23. (New) The method recited in claim 21, wherein securing the laminated conductor to the
interposer includes securing the laminated conductor adjacent to the die.
24. (New) An electronic package comprising:
 an interposer;
 a die secured to the interposer; and
 a laminated conductor secured to the interposer to mechanically support the interposer
and to supply current to the die, wherein the laminated conductor includes a positive portion that
is connected to a positive section of the interposer and a negative portion that is connected to a
negative section of the interposer.

25. (New) The electronic package of claim 24, wherein the interposer has a thickness that is less than 1 mm.

26. (New) The electronic package of claim 24, wherein the interposer is a composite metal and organic material.

27. (New) An electronic package comprising:
an interposer;
a die secured to the interposer; and
a laminated conductor secured to the interposer to mechanically support the interposer and to supply current to the die, wherein the laminated conductor includes a pair of conducting sheets separated by a dielectric layer, one of the sheets including an opening and the other sheet including a projection that extends into the opening.

28. (New) The electronic package of claim 27, wherein the sheet with the openings includes an exposed surface and the projection includes a tip that is substantially aligned with the exposed surface.

29. (New) The electronic package of claim 28, wherein the exposed surface and the tip of the projection are engaged with the interposer.

30. (New) An electronic package comprising:
an interposer;
a die secured to the interposer; and
a laminated conductor secured to the interposer to mechanically support the interposer and to supply current to the die, wherein the laminated conductor includes a pair of conducting sheets separated by a dielectric layer, one end of the laminated conductor being folded over such that each of the conducting sheets engages the interposer.

31. (New) The electronic package of claim 30, wherein the interposer includes an upper surface and a lower surface and the die and the laminated conductor are secured to the upper surface of the interposer with the laminated conductor adjacent to the die.

32. (New) The electronic package of claim 31, further comprising an electronic component that is electrically coupled to the die and is secured to the lower surface of the interposer, the interposer being thin enough to reduce the inductive loop between the electronic component and the die.

33. (New) A computer system comprising:

a bus;

a memory coupled to the bus;

a processor; and

a package including an interposer and a laminated conductor secured to the interposer, the processor being secured to the interposer such that the laminated conductor electrically connects the processor to the bus and mechanically supports the interposer during operation of the computer system, wherein the laminated conductor includes a positive portion that is connected to a positive section of the interposer and a negative portion that is connected to a negative section of the interposer.

34. (New) The computer system of claim 33, wherein the interposer includes an upper surface and a lower surface and the processor and the laminated conductor are secured to the upper surface of the interposer with the laminated conductor adjacent to the die.

35. (New) The computer system of claim 34, further comprising an electronic component that is electrically coupled to the processor and is secured to the lower surface of the interposer, the interposer being thin enough to reduce the inductive loop between the electronic component and the processor.

36. (New) A computer system comprising:

a bus;

a memory coupled to the bus;

a processor; and

a package including an interposer and a laminated conductor secured to the interposer, the processor being secured to the interposer such that the laminated conductor electrically connects the processor to the bus and mechanically supports the interposer during operation of the computer system, wherein the laminated conductor includes a pair of conducting sheets separated by a dielectric layer, one of the sheets including an opening and the other sheet including a projection that extends into the opening.

37. (New) The computer system of claim 36, wherein the sheet with the openings includes an exposed surface and the projection includes a tip that is substantially aligned with the exposed surface.

38. (New) The computer system of claim 37, wherein the exposed surface and the tip of the projection are engaged with the interposer.

39. (New) A computer system comprising:

a bus;

a memory coupled to the bus;

a processor; and

a package including an interposer and a laminated conductor secured to the interposer, the processor being secured to the interposer such that the laminated conductor electrically connects the processor to the bus and mechanically supports the interposer during operation of the computer system, wherein the laminated conductor includes a pair of conducting sheets separated by a dielectric layer, one end of the laminated conductor being folded over such that each of the conducting sheets engages the interposer.

40. (New) The computer system of claim 39, wherein the interposer has a thickness that is less than 1 mm.

41. (New) The computer system of claim 39, wherein the interposer is a composite metal and organic material.